

ELECTRONIC DEVICE

ABSTRACT

An electronic device includes a substrate and an electronic component. The substrate has a metallization trace. The metallization trace has a metallization layer and a synthetic resin layer. The metallization layer
5 has a high-melting-point metallic component and a low-melting-point metallic component. The high-melting-point metallic component and the low-melting-point metallic component are diffusion bonded together and adhered to a surface of the substrate. The synthetic resin layer is formed simultaneously with the metallization layer to cover a surface of the
10 metallization layer with a thickness in the range of 5 nm to 1000 nm. The electronic component is electrically connected to the metallization layer.

Fig. 1